

**1350V N-Channel Enhancement Mode Power IGBT**

**MAIN CHARACTERISTICS**

<b>I<sub>c</sub>@T<sub>C</sub>=25°C</b>	25A
<b>V<sub>CEs</sub></b>	1350V
<b>VCE(sat)-typ</b>	2.6V

**FEATURES**

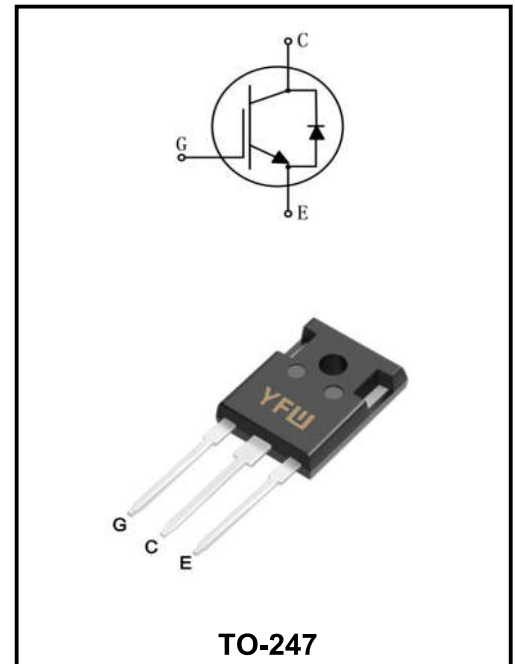
- ◆ High breakdown voltage to 1350V for improved reliability
- ◆ Trench-Stop Technology offering :  
High speed switching  
High ruggedness, temperature stable Low VCEsat  
Easy parallel switching capability due to positive temperature coefficient in VCEsat
- ◆ Soft current turn-off waveforms
- ◆ Enhanced avalanche capability

**APPLICATIONS**

- ◆ Inductive cooking
- ◆ Inverterized microwave ovens
- ◆ Resonant converters
- ◆ Soft switching applications

**MECHANICAL DATA**

- ◆ Case: TO-247/AP
- ◆ Mounting Position: Any
- ◆ Molded Plastic: UL Flammability Classification Rating 94V-0
- ◆ Lead free in compliance with EU RoHS 2011/65/EU directive
- ◆ Solder bath temperature 275°C maximum,10s per JESD 22-B106



**TO-247**

**Maximum Ratings**

Characteristics	Symbol	Value	Unit
Collector-emitter voltage	<b>V<sub>CEs</sub></b>	1350	<b>V</b>
Gate-emitter voltage	<b>V<sub>GES</sub></b>	±20	<b>V</b>
Continuous collector current (T <sub>C</sub> =25°C)	<b>I<sub>c</sub></b>	25	<b>A</b>
Pulsed collector current, tp limited by Tvjmax	<b>I<sub>CM</sub></b>	50	<b>A</b>
Diode continuous forward current (T <sub>C</sub> =100°C)	<b>I<sub>F</sub></b>	25	<b>A</b>
Diode maximum current, tp limited by Tvjmax	<b>I<sub>FM</sub></b>	50	<b>A</b>
Power dissipation(T <sub>C</sub> =25°C)	<b>P<sub>tot</sub></b>	3	<b>W</b>
Operating junction temperature range	<b>T<sub>vj</sub></b>	150	<b>°C</b>
Storage temperature range	<b>T<sub>stg</sub></b>	-55 to +150	<b>°C</b>

**Thermal characteristics**

Parameter	Symbol	Values	Unit
Thermal resistance, junction to case for IGBT	$R_{th(j-c)}$	0.48	K/ W
Thermal resistance, junction to case for Diode	$R_{th(j-c)}$	1.2	K/ W
Thermal resistance, junction to ambient	$R_{th(j-a)}$	40	K/ W

Note1:Pulse test: 300  $\mu$ s pulse width, 2 % duty cycle

**Electrical characteristics of IGBT at  $T_{vj}=25^{\circ}\text{C}$  unless otherwise specified**

Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Collector-emitter breakdown voltage	$V_{GE}=0V, I_c=250\mu A$	$B_{V_{CES}}$	1350	-	-	V
Collector-emitter leakage current	$V_{CE}=1350V, V_{GE}=0V$	$I_{CES}$	-	-	200	$\mu A$
Gate leakage current, forward	$V_{GE}=\pm 20V, V_{CE}=0V$	$I_{GES}$	-	-	$\pm 100$	nA
Gate-emitter threshold voltage	$V_{GE}=V_{CE}, I_c=250\mu A$	$V_{GE(th)}$	4	-	8	V
Collector-emitter saturation voltage Transconductance	$V_{GE}=15V, I_c=25A$	$V_{CE(sat)}$	-	-	2.6	V
	$V_{GE}=20V, I_c=25A$	$g_{fs}$	-	13	-	S
Input capacitance	$V_{CE}=25V$ $V_{GE}=0V$ $f=1MHz$	$C_{ies}$	-	2500	-	pF
Output capacitance		$C_{oes}$	-	70	-	pF
Reverse transfer capacitance		$C_{res}$	-	50	-	pF
Total gate charge		$Q_g$	-	125	-	nC
Turn-on delay time	$V_{CC}=600V$ $V_{GE}=0/15V$ $I_c=25A$ $R_G=10\Omega$ Inductive load	$td(on)$	-	180	-	ns
Rise time		$tr$	-	40	-	ns
Turn-off energy		$E_{off}$	-	0.32	-	mJ
Turn-on delay time	$V_{CC}=600V, V_{GE}=0/15V, I_c=25A,$ $R_G=10\Omega$ Inductive load, $T_{vj}=175^{\circ}\text{C}$	$td(on)$	-	220	-	ns
Rise time		$tr$	-	90	-	ns
Turn-off energy		$E_{off}$	-	0.65	-	mJ
Diode breakdown voltage	$I_R=100\mu A, T_{amb}=25^{\circ}\text{C}$	$V_{BR}$	1350	-	-	V
Diode reverse current	$V_R=1350V, T_{amb}=25^{\circ}\text{C}$	$I_R$	-	-	5	$\mu A$
Diode forward voltage	$I_F=6A, T_{vj}=25^{\circ}\text{C}$	$V_F$	-	-	2	V
	$I_F=25A, T_{vj}=25^{\circ}\text{C}$		-	-	3.5	V
Diode reverse recovery time	$I_F=0.5A, I_R=1.0A, I_{rr}=0.25A, T_{amb}=25^{\circ}\text{C}$	$trr$	-	-	75	ns

**RATINGS AND CHARACTERISTIC CURVES**

Fig. 1 Output characteristic  $V_{CE}$  vs.  $I_C$  at 25°C

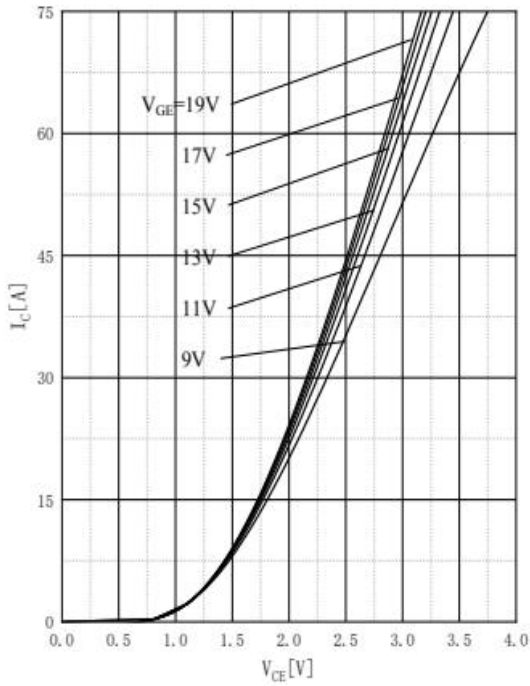


Fig. 2 Output characteristic  $V_{CE}$  vs.  $I_C$  at 175°C

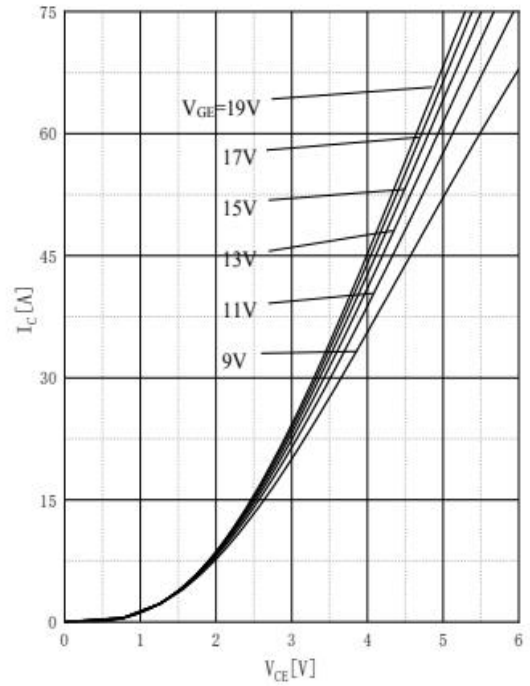


Fig. 3 Transfer characteristic  $V_{GE}$  vs.  $I_C$

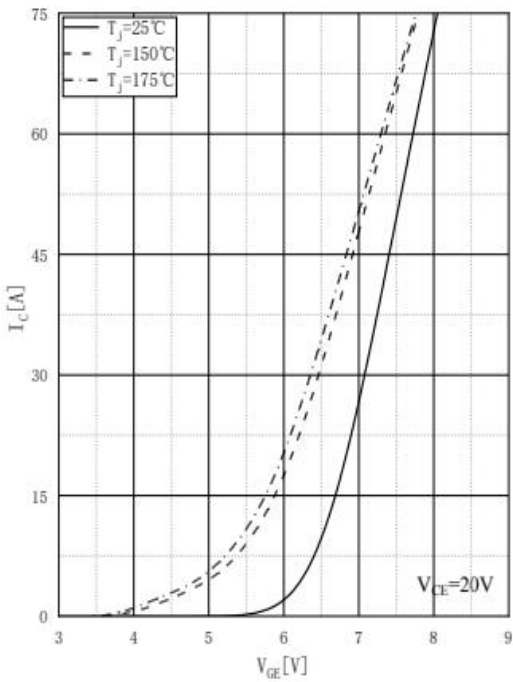
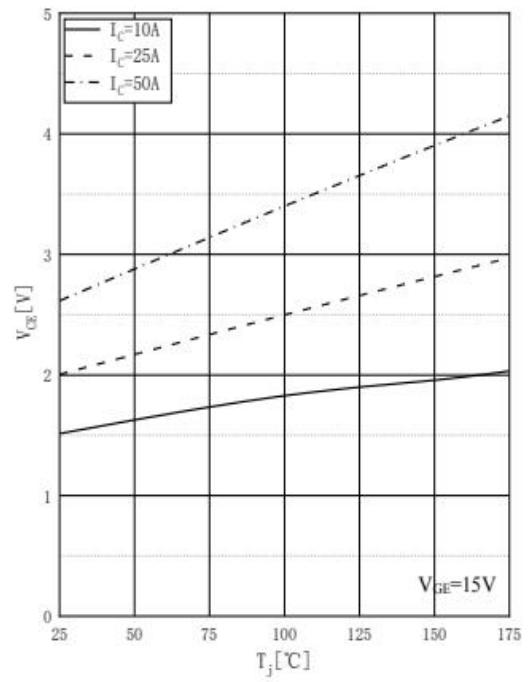


Fig. 4 Collector-emitter saturation voltage as a function of junction temperature  $V_{CEsat}$  vs.  $T_j$



**RATINGS AND CHARACTERISTIC CURVES**

Fig. 5 Gate-emitter threshold voltage as a function of junction temperature  $V_{GE(th)}$  vs.  $T_j$

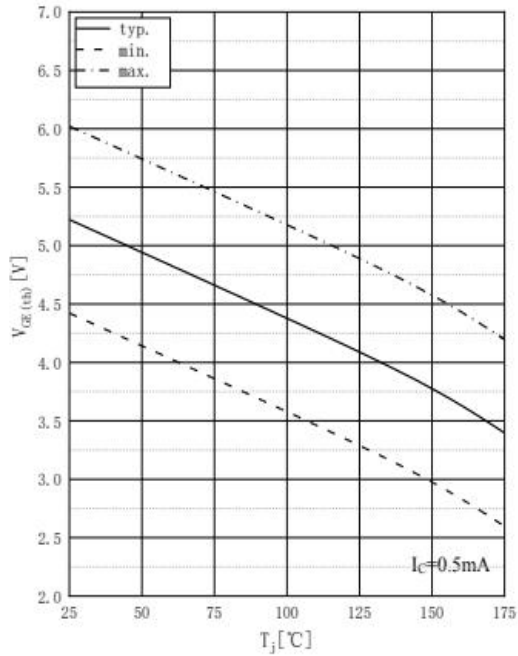


Fig. 6 Gate charge  $Q_G$

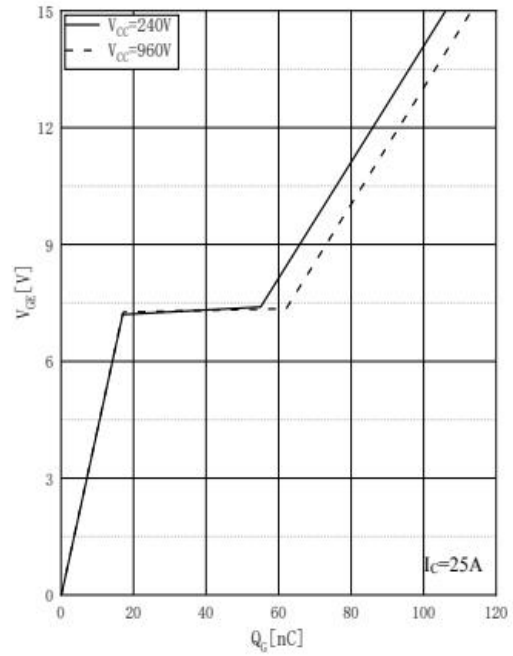


Fig. 7 Capacitance characteristic

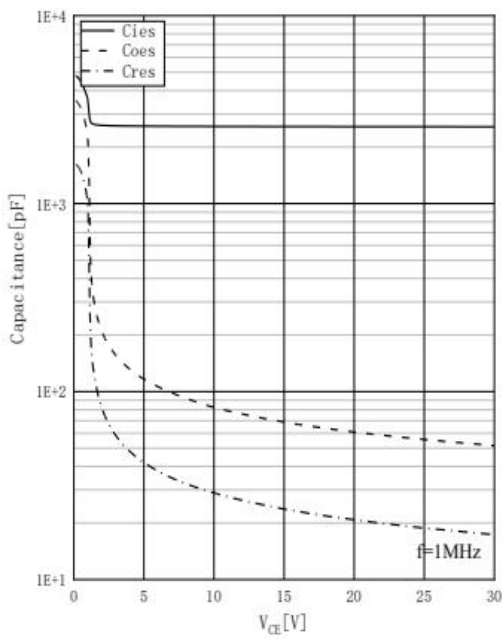
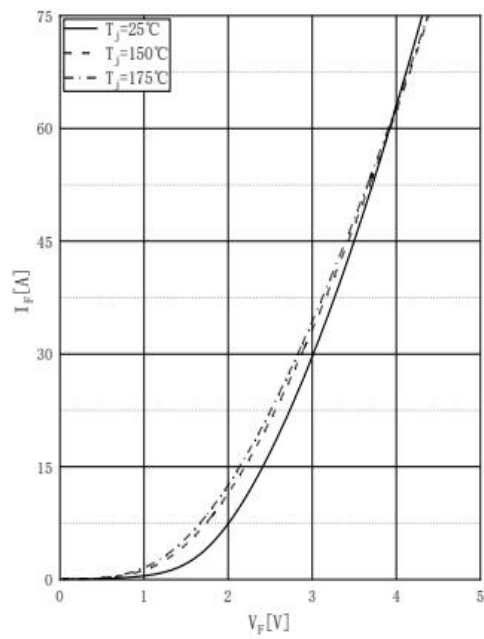


Fig. 8 Diode forward current as a function of forward voltage  $V_F$  vs.  $I_F$



**RATINGS AND CHARACTERISTIC CURVES**

Fig. 9 Diode forward voltage as a function of junction temperature  $V_F$  vs.  $T_j$

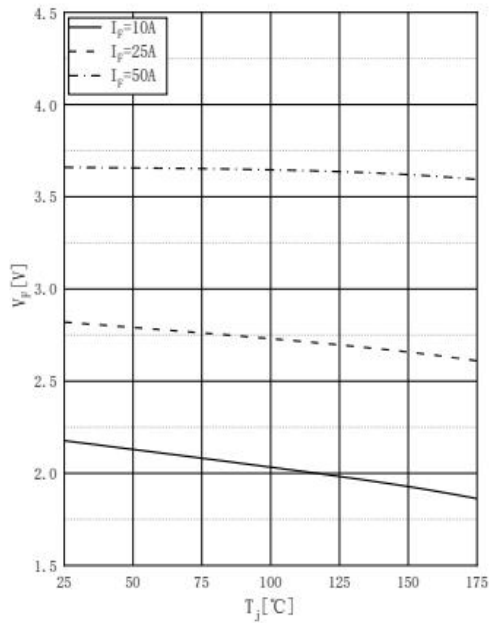


Fig. 10 Switching times vs. Collector current  $I_C$

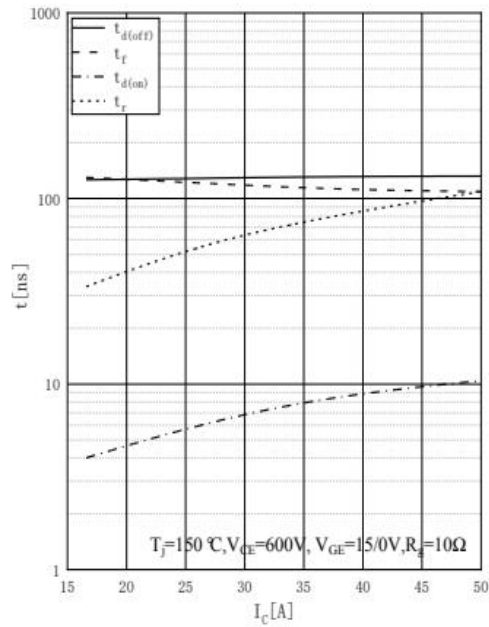


Fig. 11 Switching times vs. Gate resistor  $R_g$

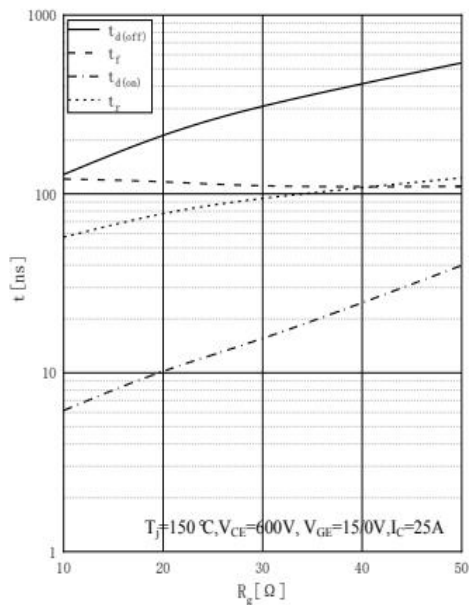
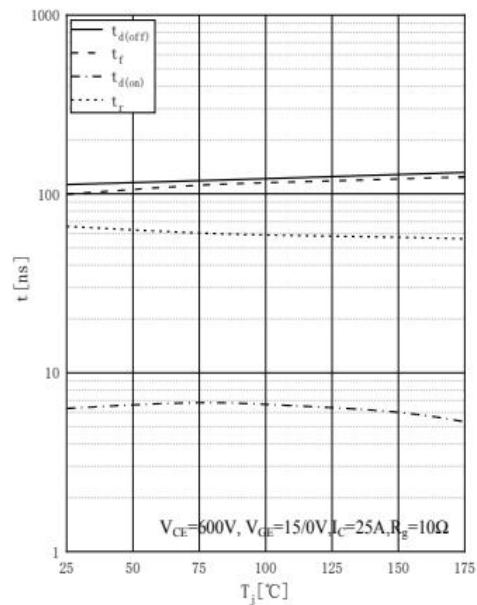


Fig. 12 Switching times vs. Junction temperature  $T_j$



**RATINGS AND CHARACTERISTIC CURVES**

Fig. 13 Switching energy loss vs. Collector current  $I_C$

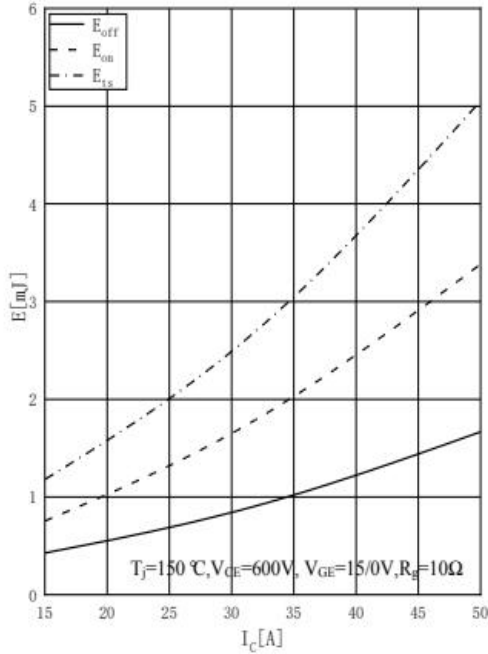


Fig. 14 Switching energy loss vs. Gate resistor  $R_g$

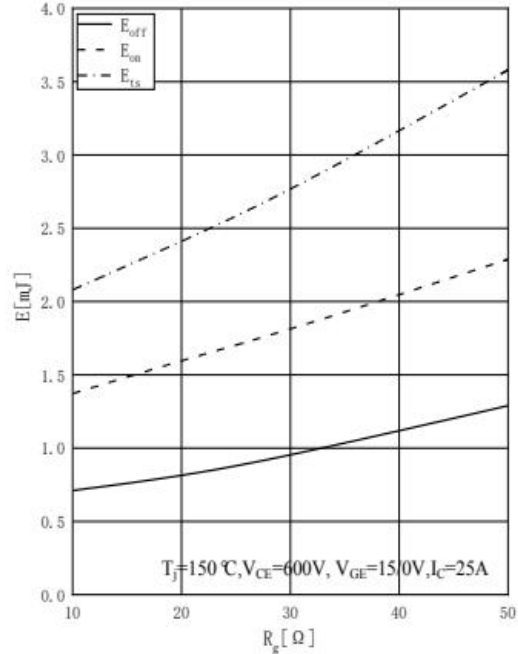


Fig. 15 Switching energy loss vs. Junction temperature  $T_j$

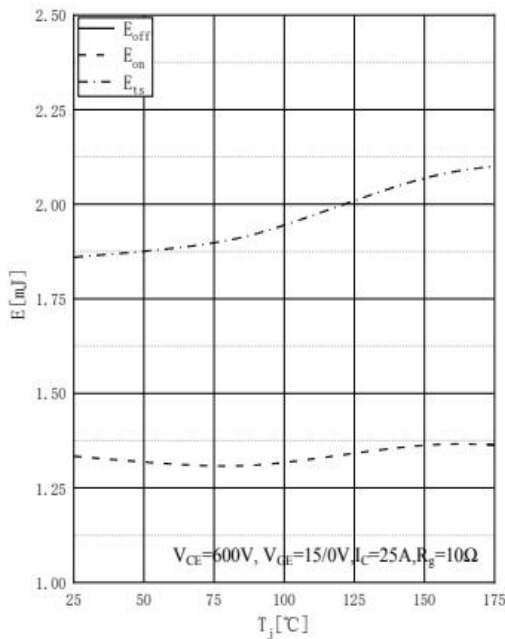
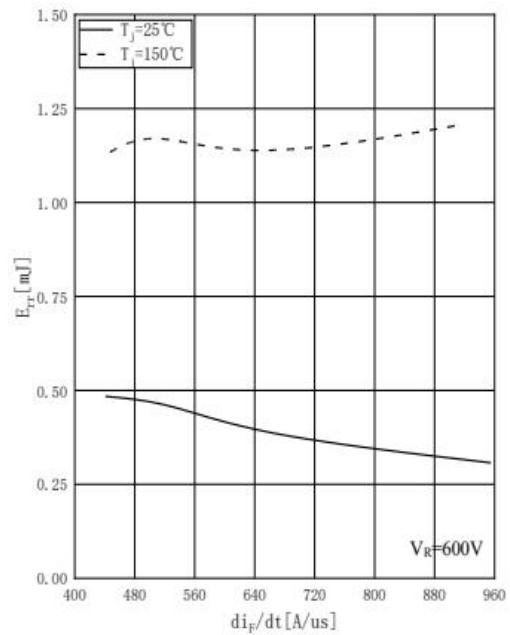


Fig. 16 Reverse recovery energy as a function of diode current slope  $E_{rr}$  vs.  $di_F/dt$



**RATINGS AND CHARACTERISTIC CURVES**

Fig. 17 Reverse recovery times as a function of diode current slope  $t_{rr}$  vs.  $di_F/dt$

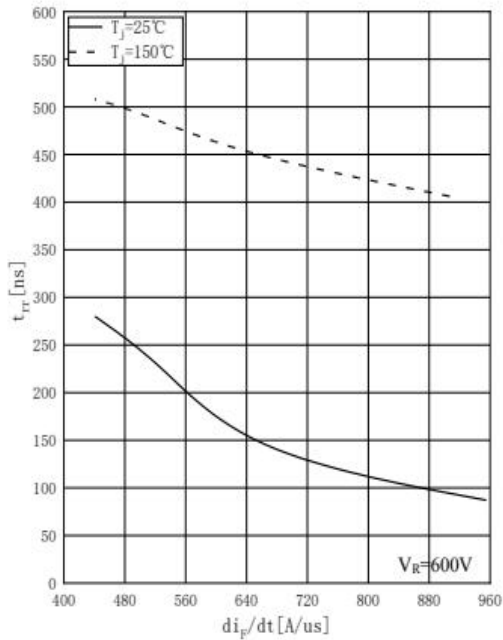


Fig. 18 Reverse recovery charge as a function of diode current slope  $Q_{rr}$  vs.  $di_F/dt$

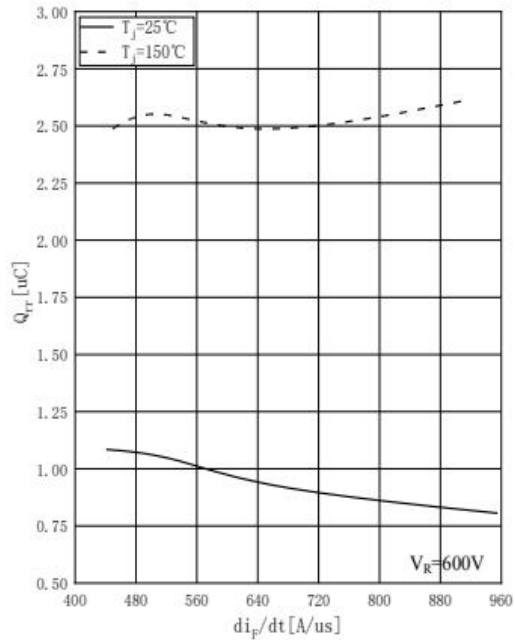


Fig. 19 Reverse recovery current as a function of diode current slope  $I_{rr}$  vs.  $di_F/dt$

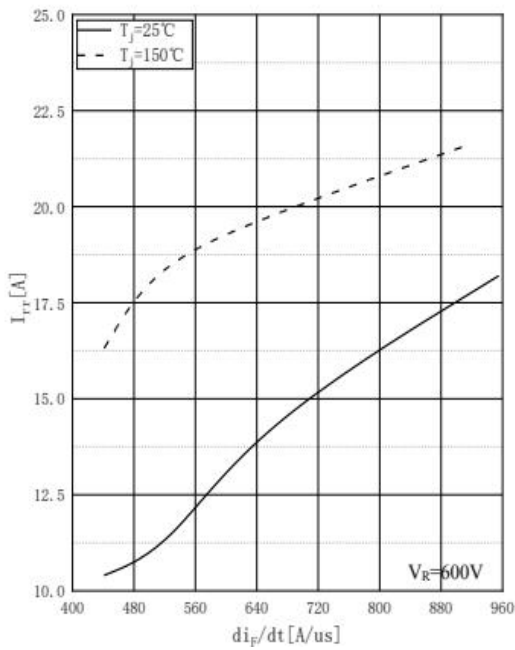
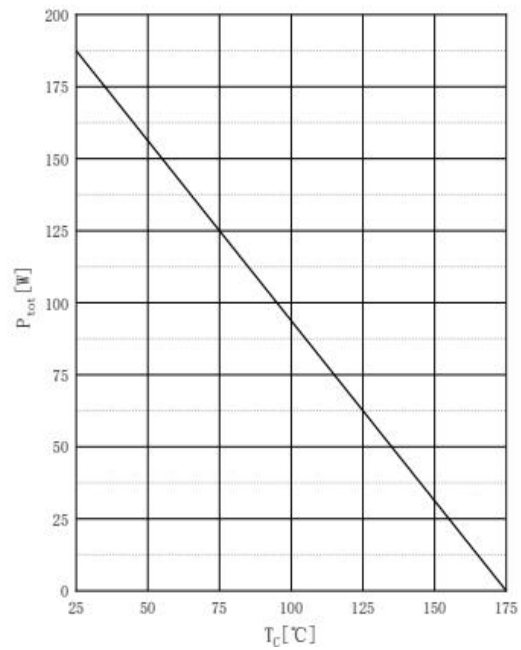


Fig. 20 Power dissipation as a function of case temperature  $P_{tot}$  vs.  $T_C$



**RATINGS AND CHARACTERISTIC CURVES**

Fig. 21 FBSOA characteristic

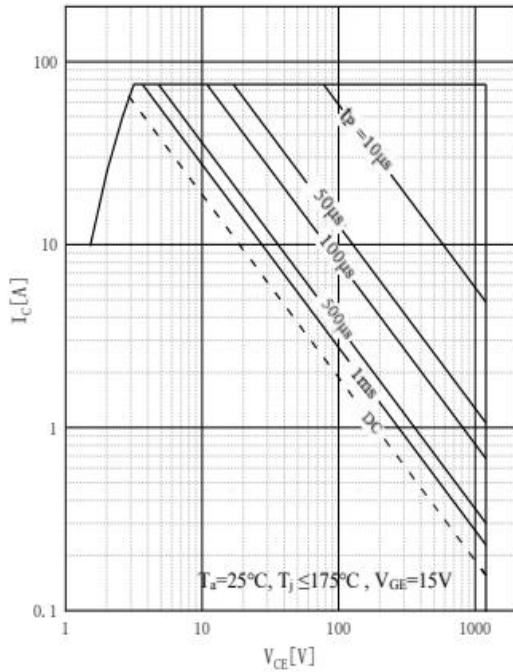


Fig. 22 IGBT transient thermal impedance  $Z_{thjc}$

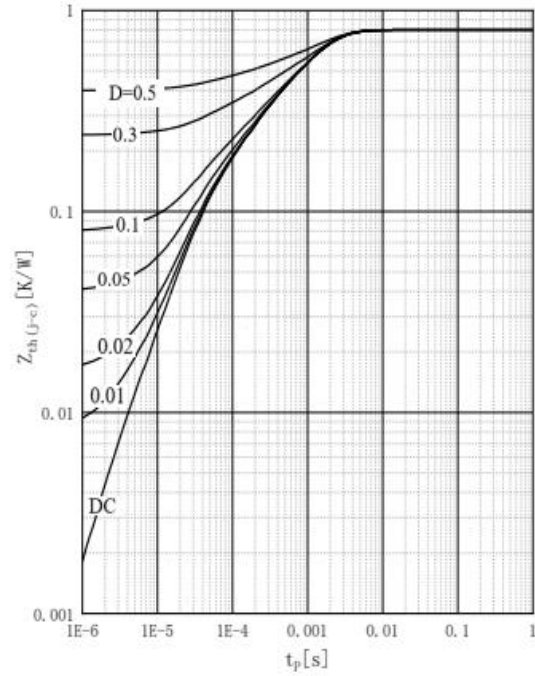
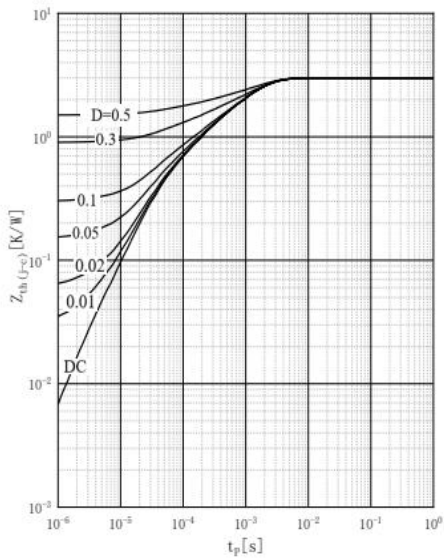
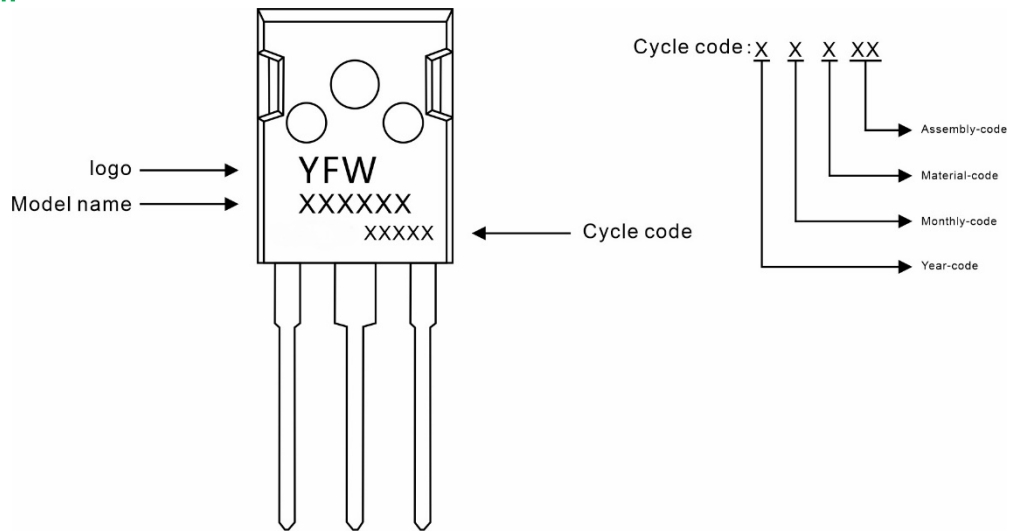


Fig. 23 Diode transient thermal impedance  $Z_{thjc}$



**Marking Diagram**



**Ordering information**

Model name	Package	Unit Weight	Base Quantity	Packing Quantity
YFWG25T135HAP	TO-247	0.209oz(5.93g)	30pcs/tube	600PCS/Box 2400PCS/Carton

**Package Dimensions**

**TO-247**

Symbol	Dimensions in mm		Dimensions in Inch	
	Min.	Max.	Min.	Max.
A	4.90	5.10	0.193	0.201
A1	1.90	2.10	0.075	0.083
A2	2.29	2.54	0.090	0.100
b	1.00	1.40	0.039	0.055
b1	2.00	2.20	0.079	0.087
b2	3.00	3.20	0.118	0.126
c	0.50	0.70	0.020	0.028
D	15.75	16.05	0.620	0.632
E	20.20	20.80	0.795	0.819
e	5.45 (BSC)		0.215 (BSC)	
e1	10.90 (BSC)		0.429 (BSC)	
F	6.05	6.25	0.238	0.246
F1	5.80	6.00	0.228	0.236
L	20.10	20.40	0.791	0.803
L1	4.05	4.35	0.159	0.171
Φ	3.50	3.70	0.138	0.146

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